

AMENDMENTS TO THE CLAIMS

The following listing of claims replaces all prior versions and listings of claims in the application.

LISTING OF CLAIMS

1. (Currently Amended) An electronic component comprising:

a plurality of circuit elements on one surface of a substrate, the circuit elements being one of ~~resistive elements~~ resistors and ~~dielectrics~~ capacitors;

a plurality of electrode pairs on the one surface of the substrate, the electrode pairs being respectively connected to the circuit elements;

an overcoat covering the circuit elements and the electrode pairs while partially exposing a part of each electrode of the electrode pairs, the exposed parts providing a plurality of lands; and

a plurality of conductive balls respectively fixedly bonded to the lands by fixedly bonded members,

the plurality of lands include first lands and second lands, and the second lands have a larger land area than the first lands,

the conductive balls are substantially equal in size to one another,

the circuit elements connected to the electrode pairs with the second lands are also connected to electrodes with lands other than the first lands, and positions of the circuit elements are offset in a plan view such that the circuit elements are laterally displaced from a shortest path between a center of each electrode of the electrode pairs in a plan view with the second lands.

2. (Previously Presented) The electronic component according to claim 1, wherein

each of the second lands is located at a position proximate to an external end of the substrate.

3. (Previously Presented) The electronic component according to claim 1, wherein

the fixedly bonding member at each land has a size that is proportional to an area of each land so that the conductive balls are fixedly bonded to an entire surface of the each land.

4-5. (Cancelled)

6. (Previously Presented) The electronic component according to claim 1, wherein

the second lands are larger in a direction of a longer side of the substrate than in a direction of a shorter side of the substrate.

7. (Previously Presented) The electronic component according to claim 1, wherein

the substrate is a tetragonal substrate and one of the second lands is located in each corner of the tetragonal substrate.

8. (Previously Presented) The electronic component according to claim 1, wherein

the substrate is a tetragonal substrate and one of the second lands is located at a position proximate to each of both external ends of the tetragonal substrate in a direction of a shorter side of the tetragonal substrate.

9. (Previously Presented) The electronic component according to claim 1, wherein

the second lands are shaped as at least one of a tetragon, an ellipse, and a tetragon having rounded corners.

10-13. (Cancelled)

14. (Previously Presented) The electronic component according to claim 1, wherein

the second lands include an Ag-Pd containing conductive paste, and an entire surface of each second land is covered with the fixedly bonding member.

15. (Previously Presented) The electronic component according to claim 2, wherein

the second lands are larger in a direction of a longer side of the substrate than in a direction of a shorter side of the substrate.

16. (Previously Presented) The electronic component according to claim 3, wherein

the second lands are larger in a direction of a longer side of the substrate larger in a direction of a shorter side of the substrate.

17. (Previously Presented) The electronic component according to claim 2, wherein

the substrate is a tetragonal substrate and one of the second lands is located in each corner of the tetragonal substrate.

18. (Previously Presented) The electronic component according to claim 3, wherein

the substrate is a tetragonal substrate and one of the second lands is located in each corner of the tetragonal substrate.

19. (Cancelled)

20. (Previously Presented) The electronic component according to claim 2, wherein

the substrate is a tetragonal substrate and one of the second lands is located at a position proximate to each of both external ends of the tetragonal substrate in a direction of a shorter side of the tetragonal substrate.

21. (Previously Presented) The electronic component according to claim 3, wherein

the substrate is a tetragonal substrate and one of the second lands is located at a position proximate to each of both external ends of the tetragonal substrate in a direction of a shorter side of the tetragonal substrate.

22. (Cancelled)

23. (Cancelled)

24. (Previously Presented) The electronic component according to claim 2, wherein

the second lands are shaped as at least one of a tetragon, an ellipse, and a tetragon having rounded corners.

25. (Previously Presented) The electronic component according to claim 3, wherein

the second lands are shaped as at least one of a tetragon, an ellipse, and a tetragon having rounded corners.

26. (Cancelled)

27. (Cancelled)

28. (Previously Presented) The electronic component according to claim 6, wherein

the second lands are shaped as at least one of a tetragon, an ellipse, and a tetragon having rounded corners.

29. (New) An electronic component comprising:

a plurality of circuit elements on one surface of a substrate, the circuit elements being one of resistors and capacitors;

a plurality of electrode pairs on the one surface of the substrate, the electrode pairs being respectively interconnected by the circuit elements;

an overcoat covering the circuit elements and the electrode pairs while partially exposing a part of each electrode of the electrode pairs, the exposed parts providing a plurality of lands; and

a plurality of conductive balls respectively fixedly bonded to the lands by fixedly bonded members,

the plurality of lands include first lands and second lands, and the second lands have a larger land area than the first lands,

the conductive balls are substantially equal in size to one another, and

the circuit elements interconnecting the electrode pairs with the second lands are positioned offset in a plan view such that the circuit elements are laterally displaced

from a shortest path between a center of each electrode of the electrode pairs with the second lands.